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OKADA et al.(10) **Pub. No.: US 2024/0213076 A1**(43) **Pub. Date: Jun. 27, 2024**(54) **SUBSTRATE PROCESSING DEVICE AND
SUBSTRATE PROCESSING METHOD****B08B 13/00** (2006.01)**H01L 21/02** (2006.01)**H01L 21/67** (2006.01)(71) Applicant: **SCREEN HOLDINGS CO., LTD.**,
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(57)

ABSTRACT

A substrate is held by an upper holding device, and a lower-surface center region of the substrate is cleaned. During this cleaning, a suction holder of a lower holding device located below the upper holding device is rotated. The substrate held by the upper holding device is transferred to a suction holder of the lower holding device. A lower-surface outer region of the substrate held by the suction holder is cleaned. After the lower-surface center region of the substrate is cleaned and until the substrate is transferred to the suction holder of the lower holding device, rotation of the lower holding device is stopped. Further, the suction holder is moved in a horizontal direction by a base device. A rotation stopping operation for the suction holder and a horizontal moving operation for the suction holder are performed such that the periods for these operation at least partially overlap with each other.

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